



Intel Custom Foundry

Leading at the Edge of Moore's Law

Intel Custom Foundry Competing in today's fabless eco-system

Keynote @Semi/Gartner Market Symposium, July 7, 2014, San Francisco

Sunit Rikhi

Vice President, Technology & Manufacturing Group
General Manager, Intel Custom Foundry



AGENDA

As a new player in the fabless eco-system,

1. The value we bring to the table
2. How we deliver on platforms of capability and services
3. How we leverage the advantages of being inside the world's leading Integrated Device Manufacturer (IDM)
4. How we face the challenges of being inside the world's leading IDM

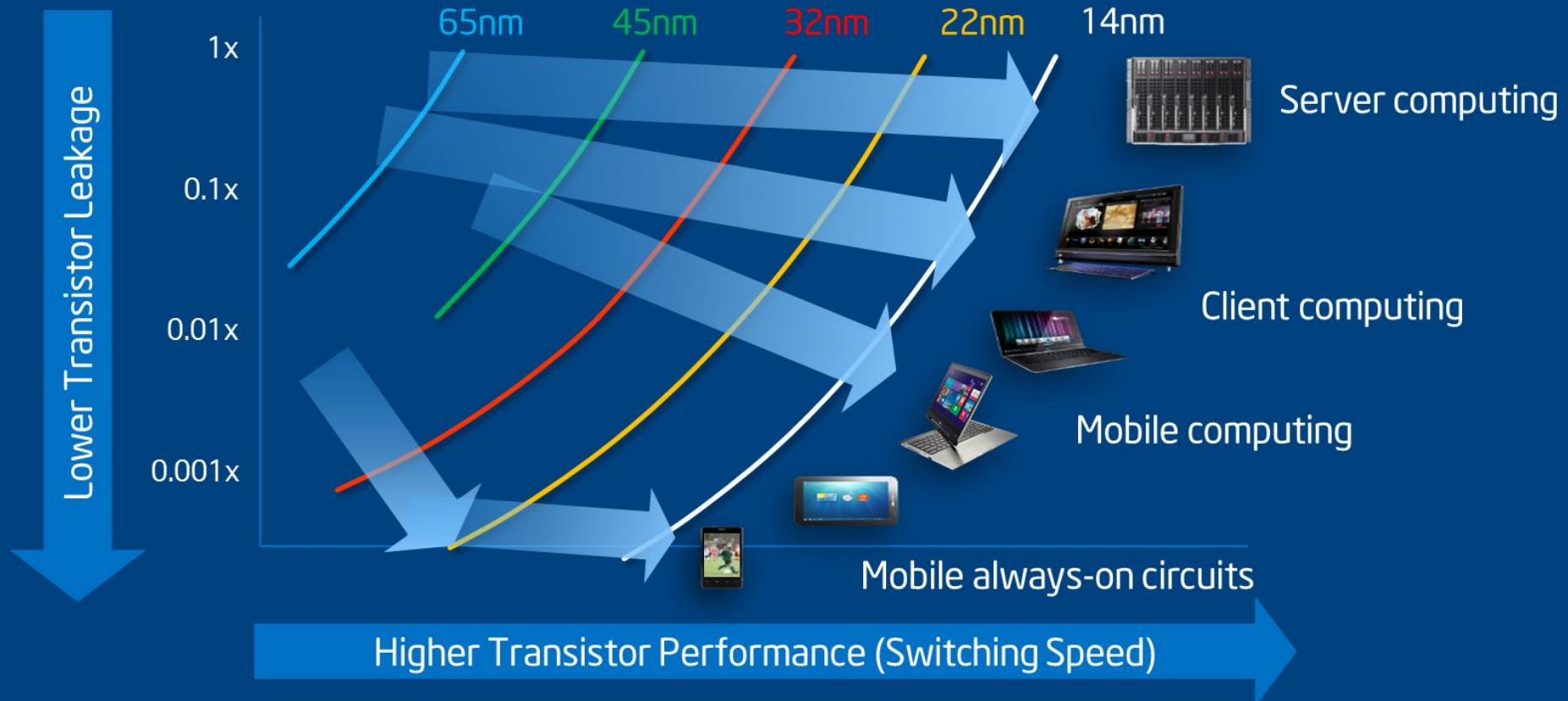
The value we bring to the table



Leadership silicon technologies

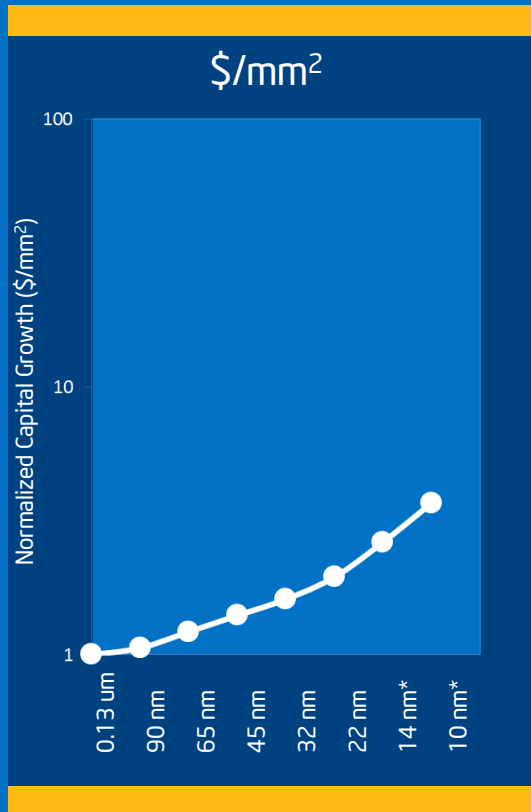
The value of better transistors

Transistor Performance/ Generation

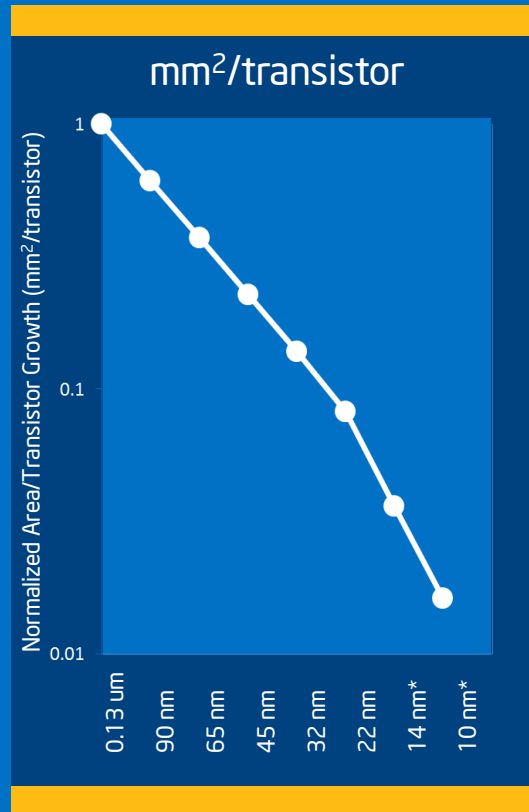


Performance per watt is the critical enabler for all

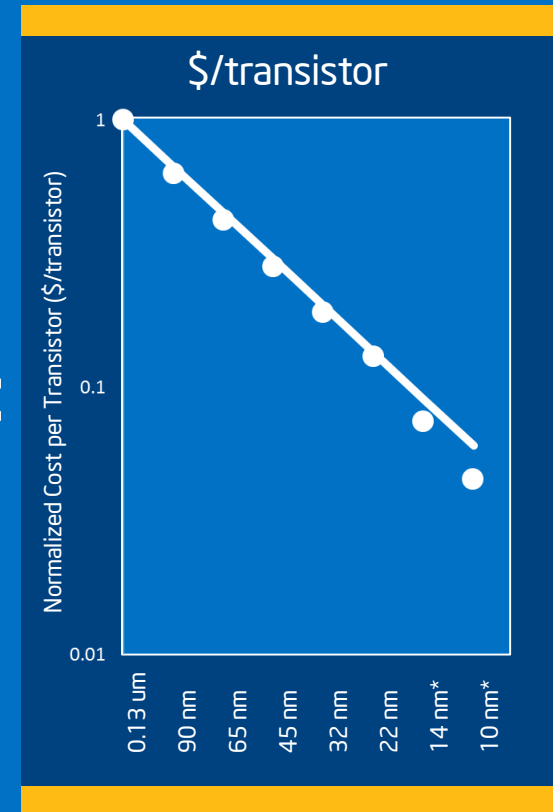
The value of decreasing cost per transistor



X



=



Source: Intel * Forecast

Density improvements offset wafer cost trends

The value of time to market



SiGe Strained Silicon (2003)

High-k Metal Gate (2007)

Tri-Gate (2011)

Competition

3.25 Years SiGe Strained Silicon (2007)

3.75 Years High-k Metal Gate (2011)

3.75 Years FinFET (2015)

Intel has ~3.5 year lead in introducing revolutionary transistor technologies



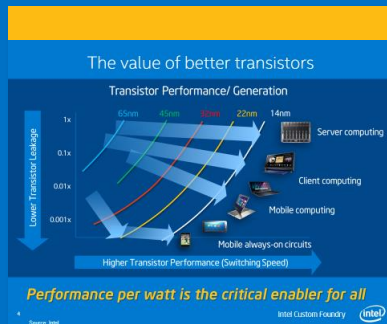
The value of confidence in pursuit of Moore's Law

Future Technology Options

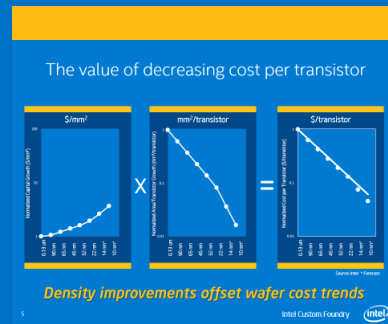


Future options subject to change

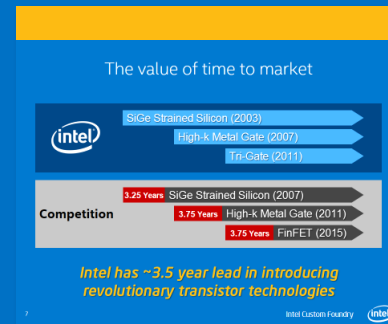
The value we bring to the table summary



Better
transistors



Decreasing
cost per
transistor



Time to market



Confidence
in pursuit of
Moore's Law

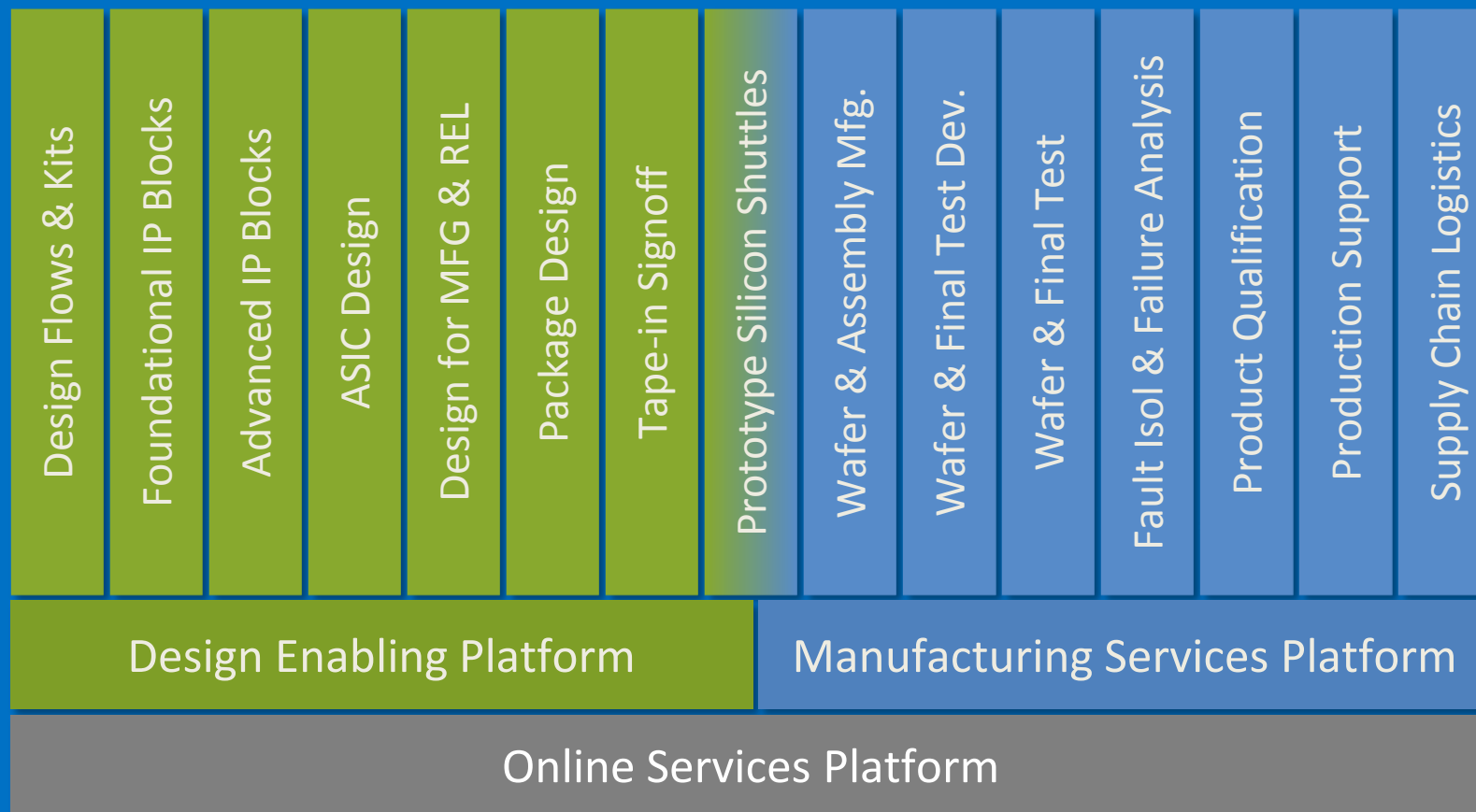
Leadership silicon technologies

AGENDA

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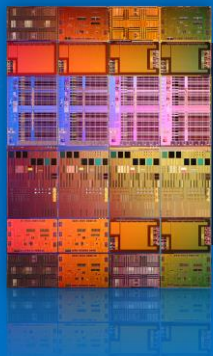
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Foundry capabilities & services platforms



Differentiated value on industry standard platforms

Prototype Silicon Shuttle Services



22nm started in 2011

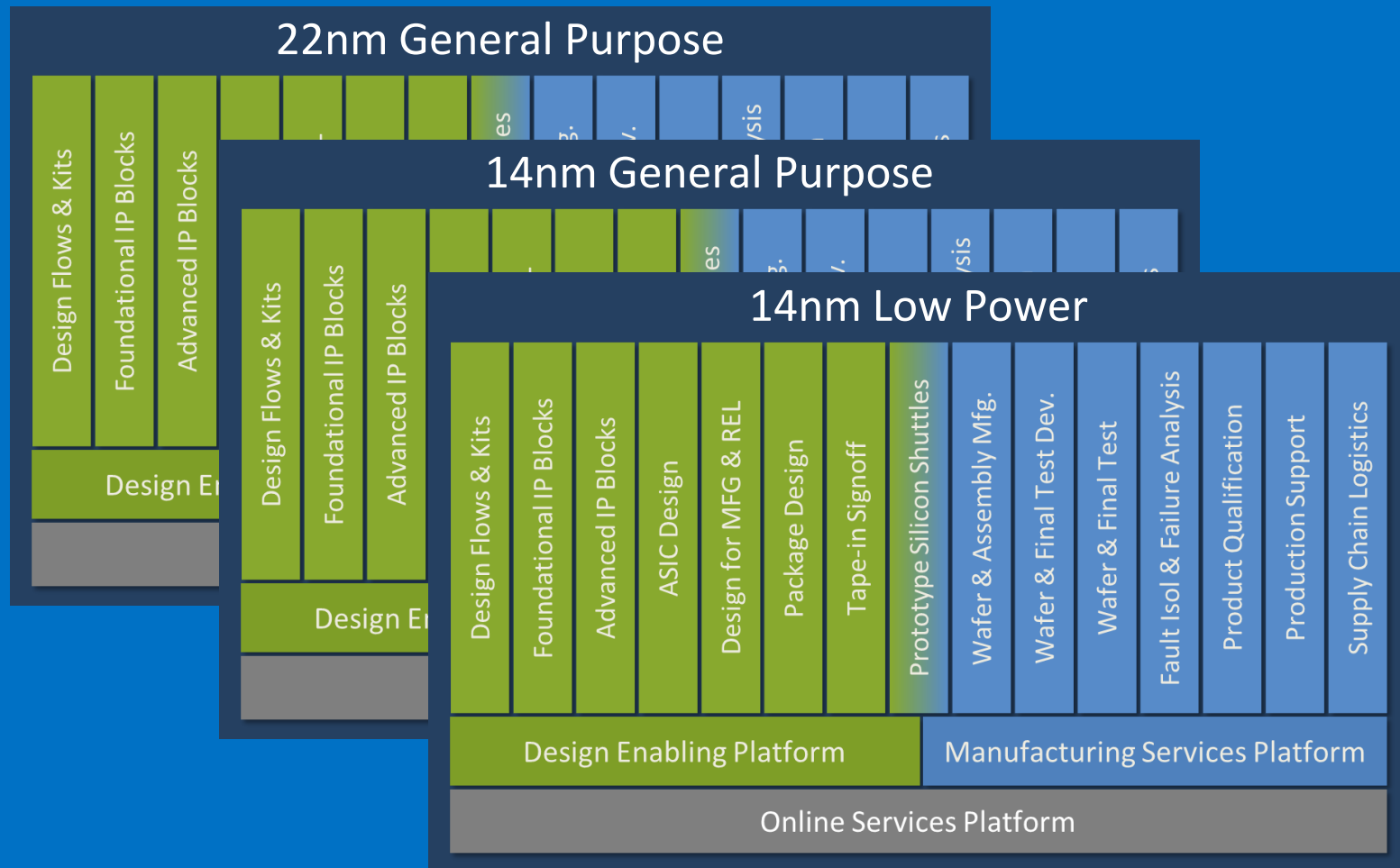


14nm started in 2013

10nm will start in 2015

125 prototype designs processed to-date

Foundry capabilities & services platforms multiple flavors



Intel Custom Foundry eco-system

Design
Services



cā dence®



synopsys®



Soft
IP



cā dence®



synopsys®

Advanced
IP



cā dence®

synopsys®

Foundation
IP



synopsys®

Design Tools
& Flows



ANSYS®

cā dence®



synopsys®

Note: Logos other than Intel's are properties of their respective companies, and order of logos is in alphabet sequence.



Eco-system collaboration announcements on June 03



ANSYS And Intel Collaborate To Deliver Power, EM And Reliability Sign-Off Reference Flow For Customers Of Intel Custom Foundry



Cadence and Intel Collaborate to Enable a 14nm Tri-gate Design Platform for Customers of Intel Custom Foundry

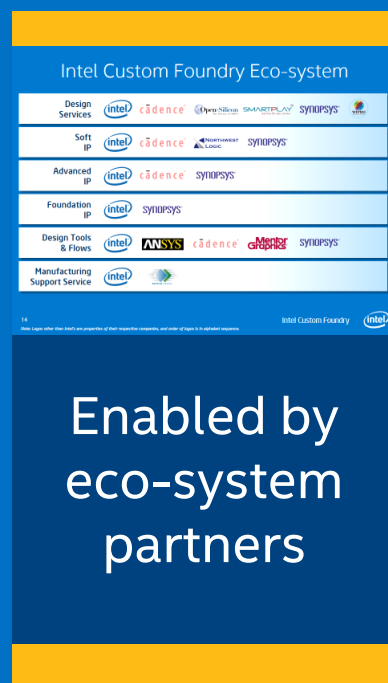
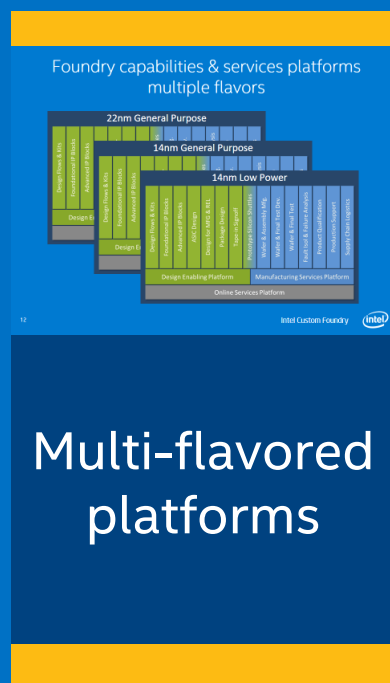


Mentor Graphics Tools Fully Enabled on Intel's 14nm Processes for Customers of Intel Custom Foundry



Synopsys and Intel Collaborate to Enable 14-nm Tri-Gate Design Platform for Use by Customers of Intel Custom Foundry

How we deliver on platforms of capability & services summary



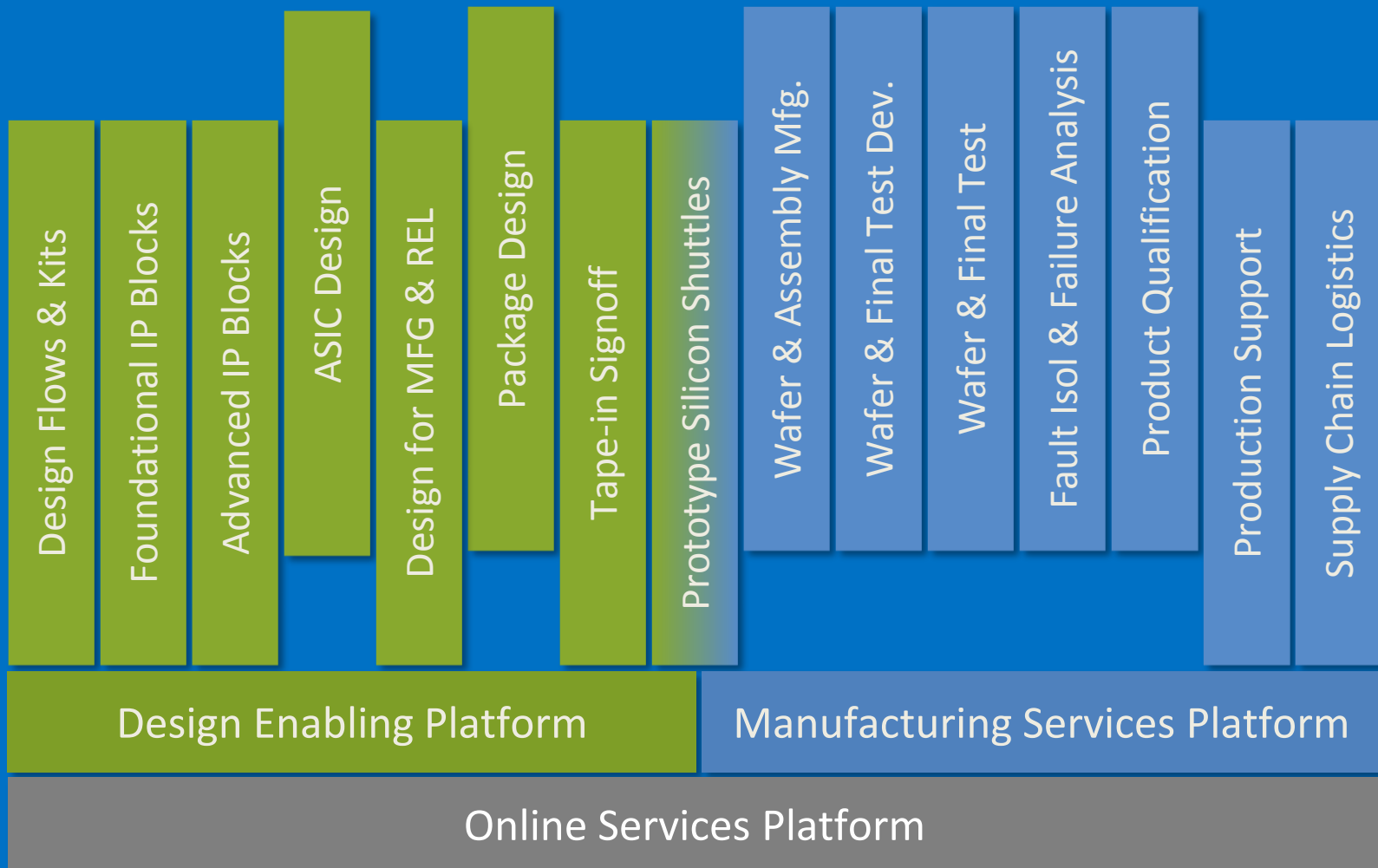
***Broad capability and services offered on
industry standard platforms***

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IDM Advantage: Foundry Plus



A fuller array of co-optimized end-to-end services

“Intel’s end-to-end foundry services dramatically accelerated Achronix’s ability to develop and ship, high-end FPGAs. That experience has already paid off and we have significantly reduced the development time required to build our current 14nm products.”

– Robert Blake, Achronix CEO

Achronix Silicon Shipped Q1 2013

Achronix Speedster22i - High-End FPGAs

- Achronix Industry “firsts”
 - Intel’s first foundry customer
 - First to ship high-end FPGAs on advanced 3-D Tri-Gate production process
 - First to embed extensive hard IP for communications applications
 - First to receive PCI-SIG PCI Express compliance for 22nm Tri-Gate advanced process



achronix
SEMICONDUCTOR CORPORATION

IDM Advantage: Packaging technology

Today

Reduced Form Factor



Intel Atom
Package on Package

Performance Boost



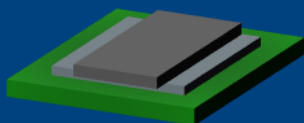
Intel Core w/Iris Pro Graphics
Heterogeneous Integration
CPU + eDRAM

Increased Functionality

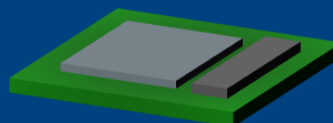


Intel Core i7
Logic Integration
CPU + PCH

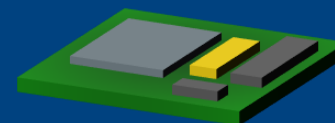
Tomorrow



3D Chip Stacking



High Density Interconnects



System in Package

*Building better products through
multi-component integration*



Altera and Intel extend manufacturing partnership to include development of multi-die devices

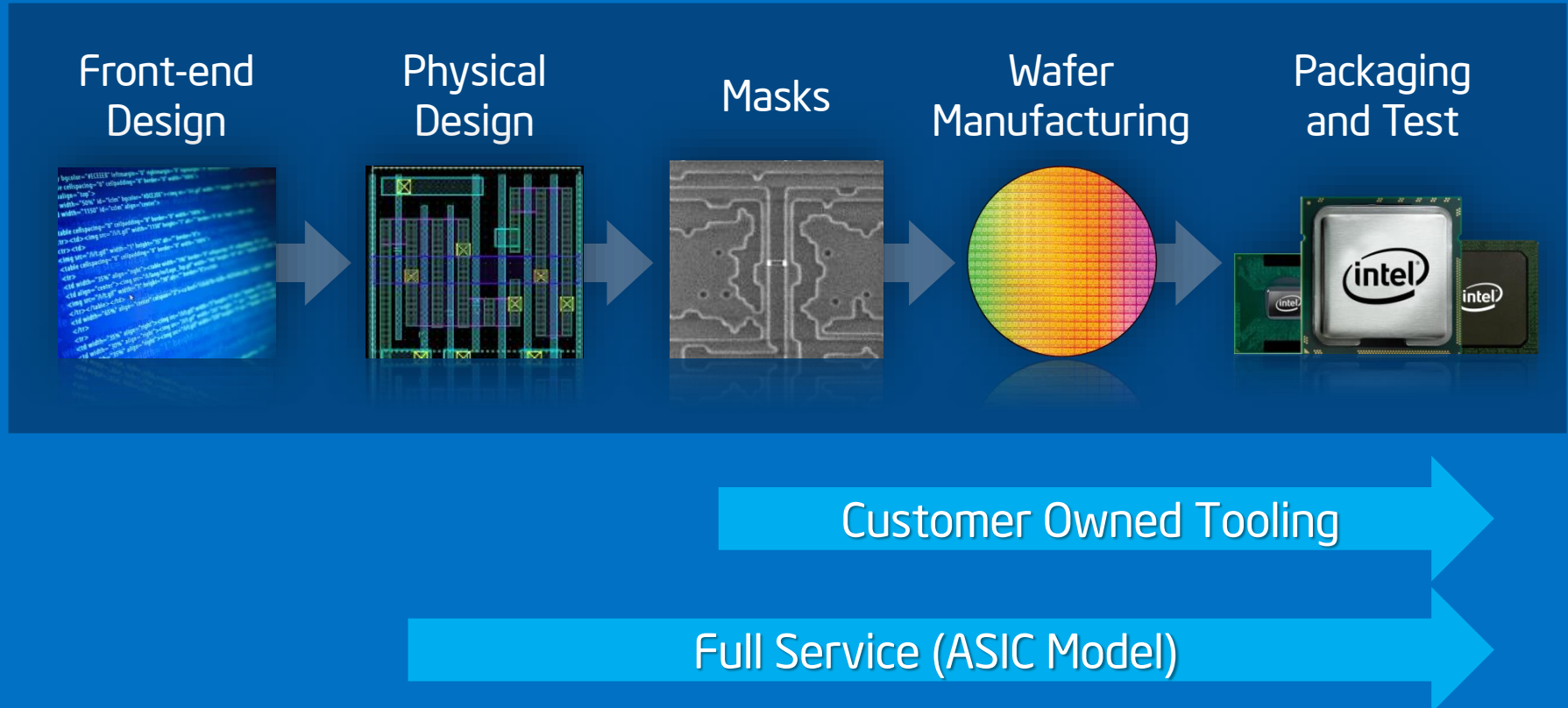
3/26/2014

"Leveraging Intel's advanced manufacturing and chip packaging capabilities will allow Altera to deliver system-in-a-package solutions that have been identified as critical to meeting overall performance requirements."

Brad Howe,
Senior VP of R&D at Altera



IDM Advantage: Flexible business models



Flexible business model (ASIC)

“Netronome's latest fully featured 200Gbps Network Flow Processor fully exploits the power/area/performance advantages of Intel's 22nm process. Intel's Foundry team provided back-end design services to deliver fully functional silicon”

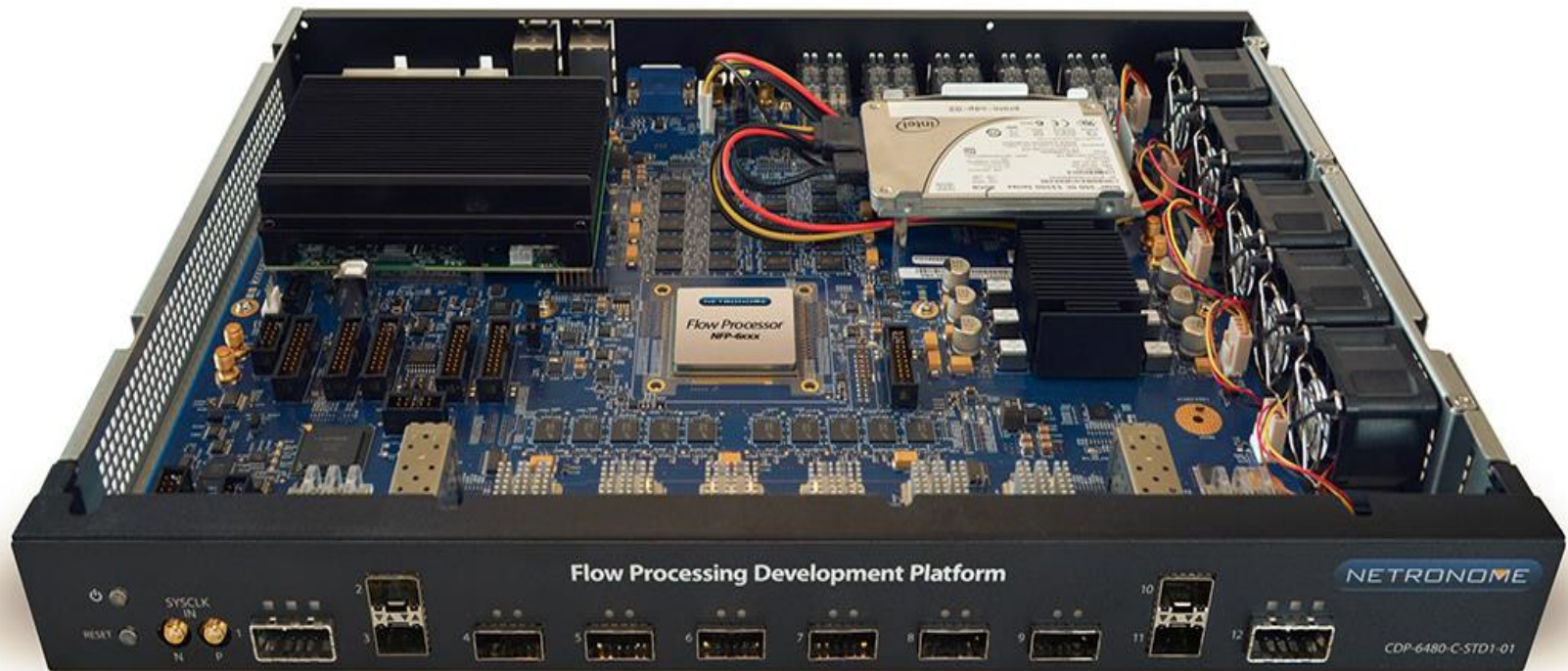
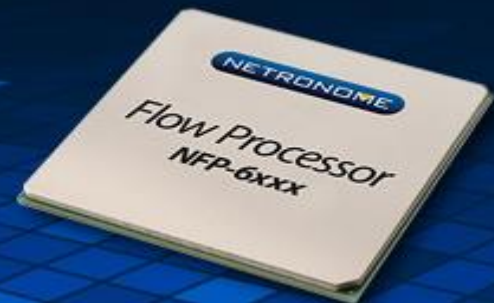
– Niel Viljoen, Netronome Founder and CEO


Shipping functional silicon to Netronome

NFP-6xxx

Netronome Flow Processor

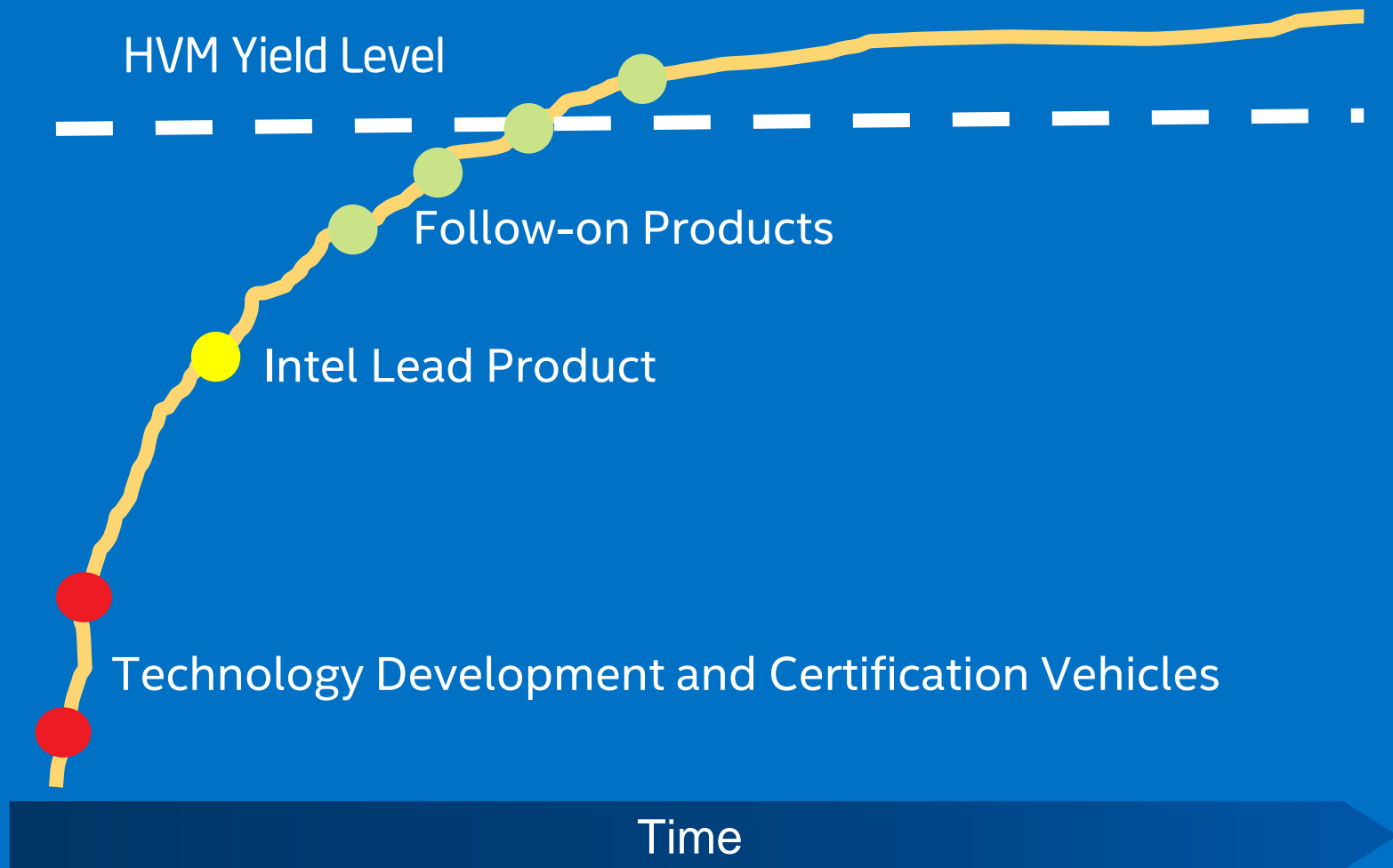
Built on Intel 22nm tri-gate transistor technology



An aerial photograph showing a multi-lane road covered in snow. Two large yellow snowplows are clearing the road, pushing snow to the sides. A line of cars is visible in the distance, waiting for the road to be cleared. The scene is set in a winter environment with snow-covered ground and trees in the background.

**IDM Advantage:
Intel's lead product
clears the way**

Starting high on the yield learning curve



“The Tabula team is delivering advanced systems solutions demonstrating industry leading capability and performance. Significantly, this is achieved with 1st silicon shipments; an outstanding example of design-team and foundry collaboration plus the design-for-manufacturability prowess Intel is known for.”

- Dennis Segers, CEO Tabula Inc.

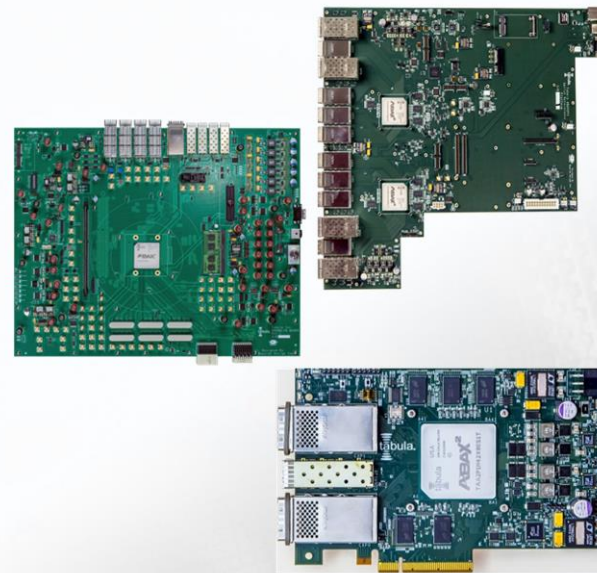
Tabula Advanced Systems powered by Intel silicon technologies

ABAX² – P1 Programmable Logic Family - Built on Intel 22nm



- Industry's highest performance PLD
 - Up to 2 GHz performance
- 23.3 Mbytes on-chip RAM
 - 104 Tb/s throughput (Industry's highest)
- State-of-the-art hard IP blocks
 - 10/40/100G EMACs and DDR3 controllers
- Unmatched system performance
 - 4 x 100G L2-L4 switch: a PLD 1st
 - Highest performance RegEx acceleration

100G Pre-engineered Solutions



- Switch
- Bridge
- Search

Advantages of IDM summary

21

IDM Advantage
Silicon Co-Optimized Packaging Technology

	Reduced Form Factor	Performance Boost	Increased Functionality
Today	 Intel Atom Package on Package	 Intel Core with Pro Graphics Heterogeneous Integration CPU + eDRAM	 Intel Core i7 Logic Integration CPU + PCH
Tomorrow	 3D Chip Stacking	 High Density Interconnects	 System in Package

Building Better Products Through Multi-Component Integration

Intel Custom Foundry

Co-optimized

22

IDM Advantage:
Intel's lead product
clears the way

Product
proven

23

IDM Advantage: Flexible Business Models

Front-end Design → Physical Design → Masks → Wafer Manufacturing → Packaging and Test

Customer Owned Tooling

Full Services (ASIC Model)

Benefits to Foundry Customers:
1) Co-Optimization Value
2) Integrated Supply Chain

Intel Custom Foundry

End-to-end

Capability and Services

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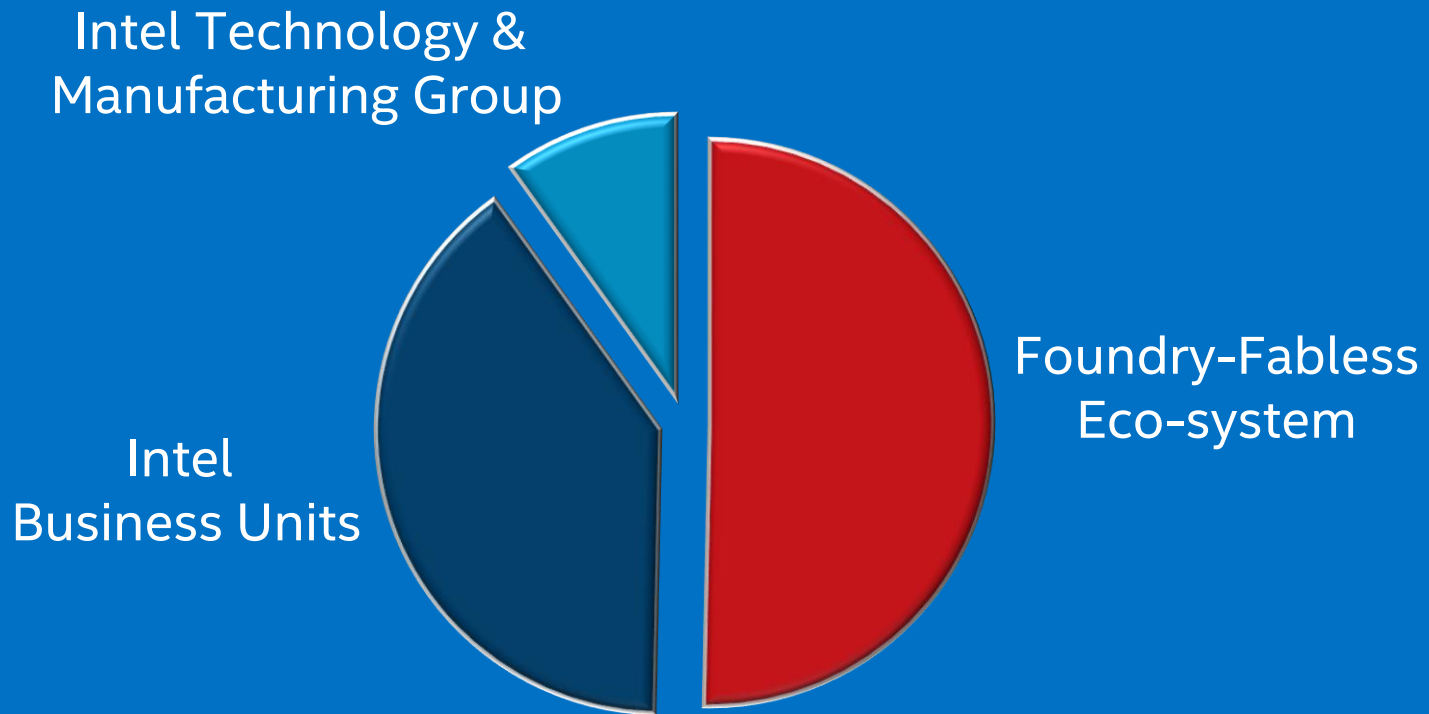
IDM Challenge:

Developing the insights, culture & expertise

.. to **serve** the needs of an expanded marketplace which includes the traditional Intel Business Units and the new Intel Foundry Customers

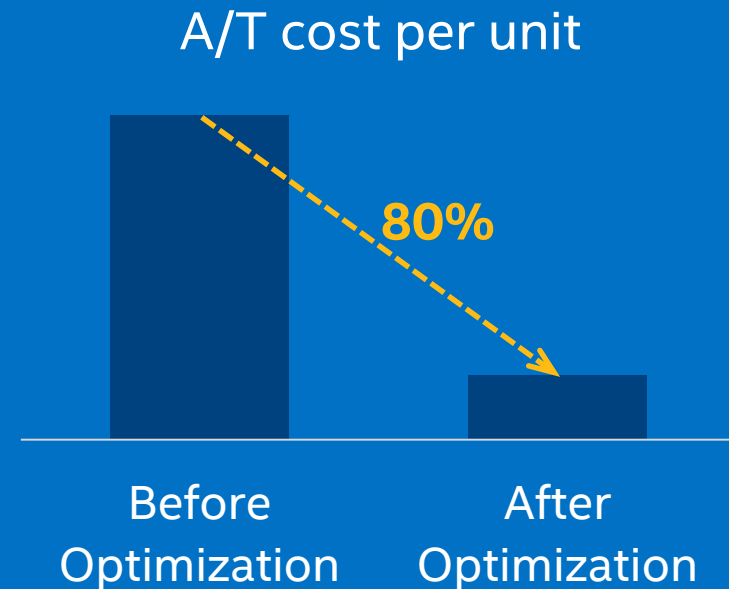
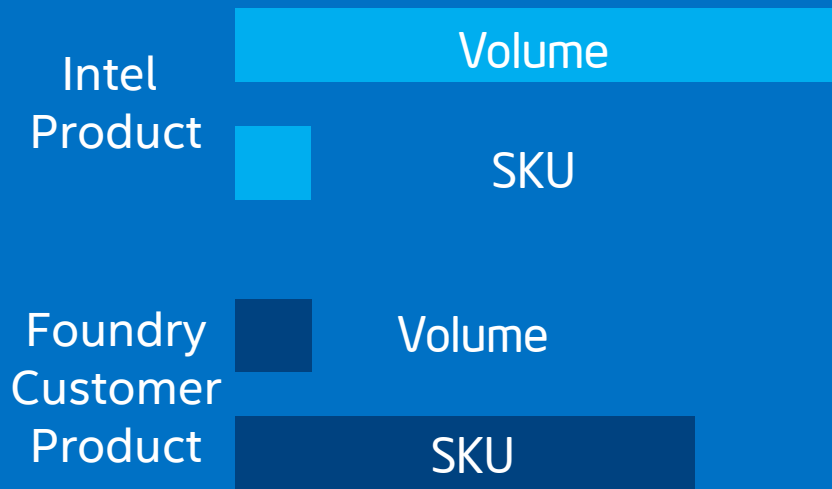
Response:

Reflect the marketplace in our workforce
and maintain a learning & serving environment



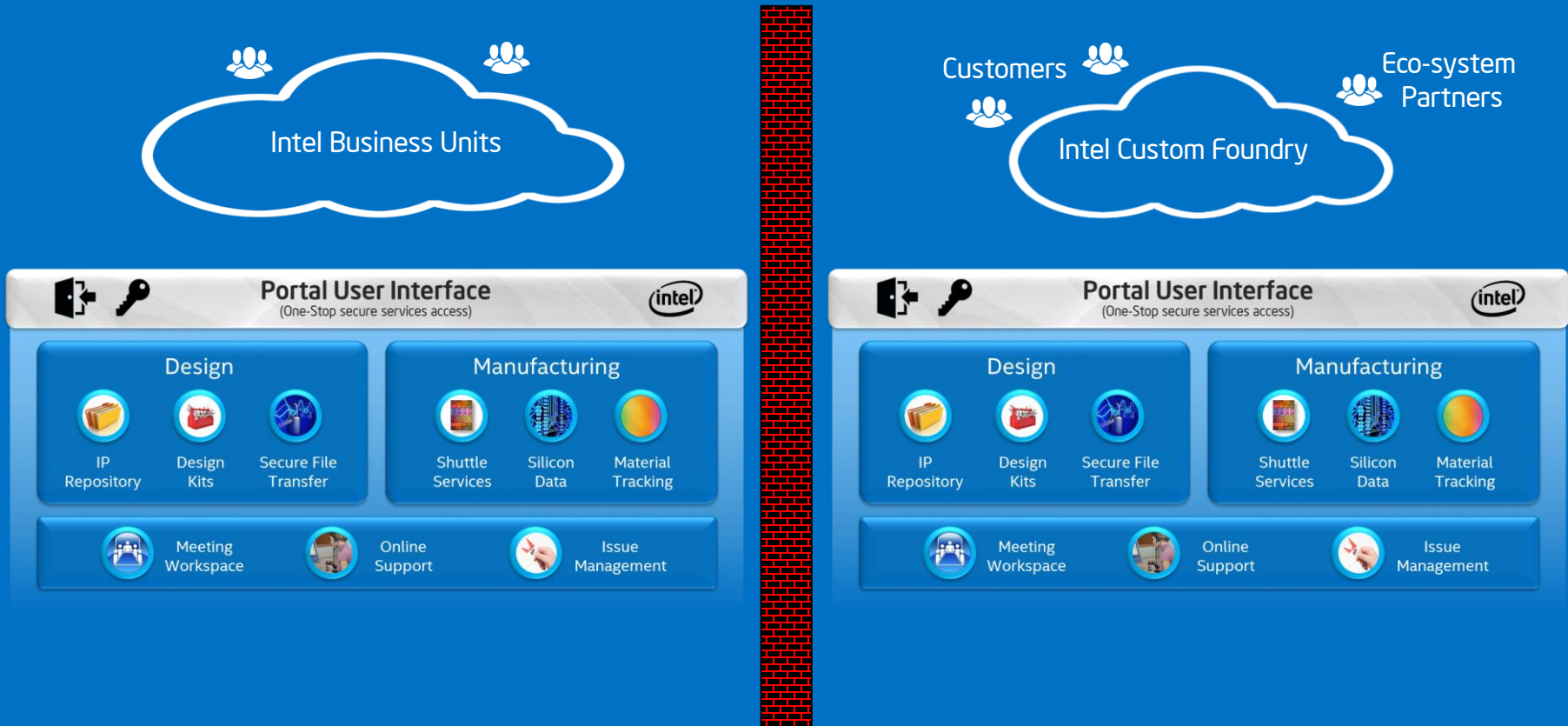
Sources of Intel Custom Foundry Workforce

IDM Challenge: High-mix-low-volume Configuration



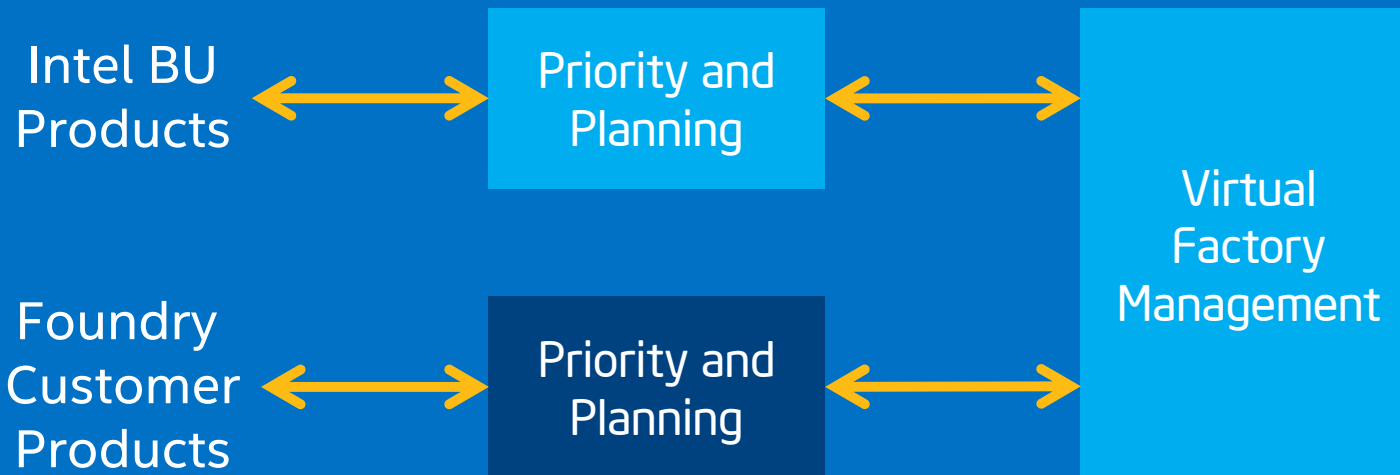
Response:
Configuration optimization in tooling & set up

IDM Challenge: Separation of Intel Business Unit & customer IP



Response: Separation by infrastructure design

IDM Challenge: Managing customers' priority and capacity

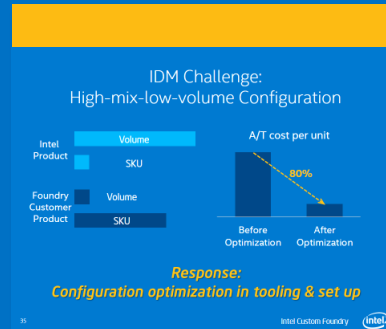


Response: Separate priority and planning process

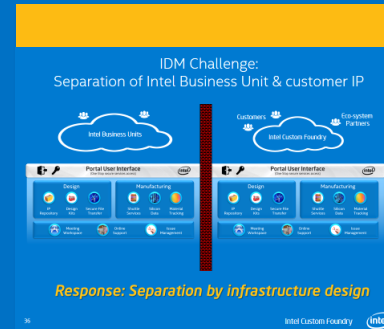
Challenges of IDM summary



Marketplace
insight &
expertise



Operational
Optimization



IP separation



Priority and
capacity
planning

There is an effective response for every challenge

Intel Custom Foundry announced customers



*Note: This list of customers does not include those did not disclose relationship with Intel.
Logos other than Intel's are properties of their respective companies, and order of logos is in alphabet sequence.*

Intel Custom Foundry's Newest Customer

*“Intel’s 14nm Tri-Gate process technology is very important to develop the next generation SoCs. **We will deliver highly improved performance and power advantages with next generation SoCs** by leveraging Intel’s 14nm tri-gate process technology through our collaboration.”*

*– Yoshifumi Okamoto
Director, SLSI Business Division
Panasonic Corporation*

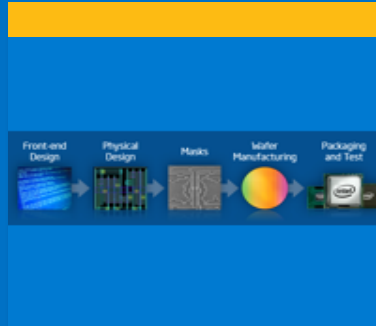
Summary of this talk



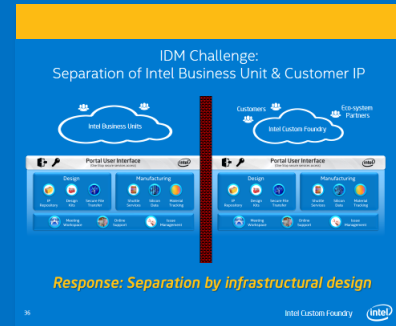
Our Value:
Leadership
silicon
technologies



Delivered on:
Industry
standard
platforms



Enhanced by:
our IDM
advantages



While responding to:
Our IDM
challenges

Growth ahead!

Intel Custom Foundry



Leading at the Edge of Moore's Law

Thank you



Intel Custom Foundry



Leading at the Edge of Moore's Law

Q & A



Risk Factors

The above statements and any others in this document that refer to plans and expectations for the second quarter, the year and the future are forward-looking statements that involve a number of risks and uncertainties. Words such as “anticipates,” “expects,” “intends,” “plans,” “believes,” “seeks,” “estimates,” “may,” “will,” “should” and their variations identify forward-looking statements. Statements that refer to or are based on projections, uncertain events or assumptions also identify forward-looking statements. Many factors could affect Intel’s actual results, and variances from Intel’s current expectations regarding such factors could cause actual results to differ materially from those expressed in these forward-looking statements. Intel presently considers the following to be important factors that could cause actual results to differ materially from the company’s expectations. Demand for Intel’s products is highly variable and, in recent years, Intel has experienced declining orders in the traditional PC market segment. Demand could be different from Intel’s expectations due to factors including changes in business and economic conditions; consumer confidence or income levels; customer acceptance of Intel’s and competitors’ products; competitive and pricing pressures, including actions taken by competitors; supply constraints and other disruptions affecting customers; changes in customer order patterns including order cancellations; and changes in the level of inventory at customers. Intel operates in highly competitive industries and its operations have high costs that are either fixed or difficult to reduce in the short term. Intel’s gross margin percentage could vary significantly from expectations based on capacity utilization; variations in inventory valuation, including variations related to the timing of qualifying products for sale; changes in revenue levels; segment product mix; the timing and execution of the manufacturing ramp and associated costs; excess or obsolete inventory; changes in unit costs; defects or disruptions in the supply of materials or resources; and product manufacturing quality/yields. Variations in gross margin may also be caused by the timing of Intel product introductions and related expenses, including marketing expenses, and Intel’s ability to respond quickly to technological developments and to introduce new products or incorporate new features into existing products, which may result in restructuring and asset impairment charges. Intel’s results could be affected by adverse economic, social, political and physical/infrastructure conditions in countries where Intel, its customers or its suppliers operate, including military conflict and other security risks, natural disasters, infrastructure disruptions, health concerns and fluctuations in currency exchange rates. Intel’s results could be affected by the timing of closing of acquisitions, divestitures and other significant transactions. Intel’s results could be affected by adverse effects associated with product defects and errata (deviations from published specifications), and by litigation or regulatory matters involving intellectual property, stockholder, consumer, antitrust, disclosure and other issues, such as the litigation and regulatory matters described in Intel’s SEC filings. An unfavorable ruling could include monetary damages or an injunction prohibiting Intel from manufacturing or selling one or more products, precluding particular business practices, impacting Intel’s ability to design its products, or requiring other remedies such as compulsory licensing of intellectual property. A detailed discussion of these and other factors that could affect Intel’s results is included in Intel’s SEC filings, including the company’s most recent reports on Form 10-Q, Form 10-K and earnings release.